#### TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

# TD62551SG, TD62553SG, TD62554SG, TD62555SG

### 4CH SINGLE DRIVER: COMMON EMITTER

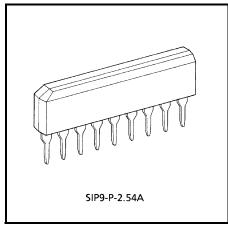
The TD62551SG series are comprised of four NPN transistor arrays.

Applications include relay, hammer, lamp and display (LED) drivers.

This devices are a product for the Pb free(Sn-Ag).

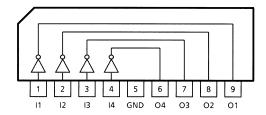
#### **FEATURES**

- Output current (single output) 150 mA (Max)
- High sustaining voltage output 25 V (Min)
- Low saturation voltage VCE (sat) = 0.5 V @IOUT = 50 mA
- Inputs compatible with various types of logic.
- TD62551SG : External
- TD62553SG :  $R_{IN} = 2.7 \text{ k}\Omega \dots TTL$ , 5 V CMOS
- :  $R_{IN} = 10.5 \text{ k}\Omega \dots 6 \sim 15 \text{ V PMOS}$ , CMOS • TD62554SG
- TD62555SG:  $R_{IN} = 20 \text{ k}\Omega \dots 12 \sim 24 \text{ V PMOS}$
- : SIP-9 pin Package type

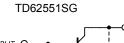


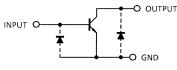
Weight: 0.92 g (Typ.)

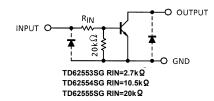
#### PIN CONNECTION



### **SCHEMATICS (EACH DRIVER)**







Note: The input and output parasitic diodes cannot be used as clamp diodes.



# MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Collector-Emitter Voltage	V <sub>CEO</sub>	25	V
Collector-Base Voltage	V <sub>CBO</sub>	35	٧
Collector Current	IC	150	mA / ch
Input Voltage	V <sub>IN</sub> (Note 1)	20	V
Input Current	I <sub>IN</sub> (Note 2)	10	mA
Power Dissipation	P <sub>D</sub> (Note 3)	0.75	W
Operating Temperature	T <sub>opr</sub>	-40~85	°C
Storage Temperature	T <sub>stg</sub>	-55~150	°C

Note 1: Except TD62551SG Note 2: Only TD62551SG

Note 3: Delated above 25°C in the proportion of 6.0mW / °C.

## RECOMMENDED OPERATING CONDITIONS (Ta = -40-85°C)

CHARAC	TERISTIC	SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT
Collecter-Emitter \	√oltage	$V_{CEO}$	_	0	_	25	V
Collecter-Base Vo	ltage	V <sub>CBO</sub>	_	0	_	35	V
Collector Current	TD62551SG TD62553SG	Ic	_	0	_	100	mA / ch
	TD62554SG			0	_	80	
	TD62555SG			0	_	60	
Input Voltage	TD62553SG TD62554SG TD62555SG	V <sub>IN</sub>	_	0	_	20	V
Input Current	TD62551SG	I <sub>IN</sub>	_	0	_	5	mA
Power Dissipation		P <sub>D</sub>	_	_	_	0.27	W

## **ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

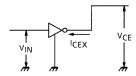
			TEST					
CHARAC	CTERISTIC	SYMBOL	CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Output Leakage C	Current	I <sub>CEX</sub>	1	V <sub>CE</sub> = 25 V, V <sub>IN</sub> = 0 V	_	_	10	μA
Collector-Emitter Saturation Voltage		VCE (sat) 2	2	I <sub>IN</sub> = 0.5 mA, I <sub>C</sub> = 10 mA	_	0.15	0.2	V
			2	I <sub>IN</sub> = 2.5 mA, I <sub>C</sub> = 50 mA	_	0.35	0.5	
DC Current Transfer Ratio	(Note 1)	h <sub>FE</sub>	2	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 10 mA	60	_	400	
	(Note 2)				50	_	400	_
Input Voltage	TD62553SG	V <sub>IN (ON)</sub>	3	I <sub>IN</sub> = 0.5 mA, I <sub>C</sub> = 10 mA	1.7	2.1	2.5	
	TD62554SG				4.4	6.0	7.6	V
	Td62555SG				7.7	10.7	13.8	
Turn-On Delay		t <sub>ON</sub>	4	$V_{OUT}$ = 25 V, R <sub>L</sub> = 210 $\Omega$ C <sub>L</sub> = 15 pF	_	100	_	ns
Turn-Off Delay		t <sub>OFF</sub>			_	500	_	115

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Note 1: Except TD62551SG Note 2: Only TD62551SG

### **TEST CIRCUIT**

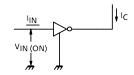
## 1. I<sub>CEX</sub>



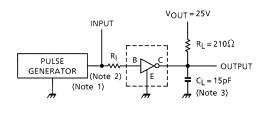
## 2. h<sub>FE</sub>, V<sub>CE (sat)</sub>

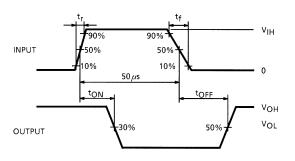
$$h_{FE} = \frac{I_C}{I_{IN}}$$

### 3. V<sub>IN (ON)</sub>



### 4. ton, toff





Note 1: Pulse Width 50  $\mu$ s, Duty Cycle 10% Output Impedance 50  $\Omega$ ,  $t_f \le 5$  ns,  $t_f \le 10$  ns

Note 2: See right.

Note 3: C<sub>L</sub> includes probe and jig capacitance.

#### INPUT CONDITION

TYPE NUMBER	R <sub>I</sub>	V <sub>IH</sub>
TD62551SG	2.7 kΩ	3 V
TD62553SG	0 Ω	3 V
TD62554SG	0 Ω	10 V
TD62555SG	0 Ω	14 V

### **PRECAUTIONS for USING**

This IC does not integrate protection circuits such as overcurrent and overvoltage protectors.

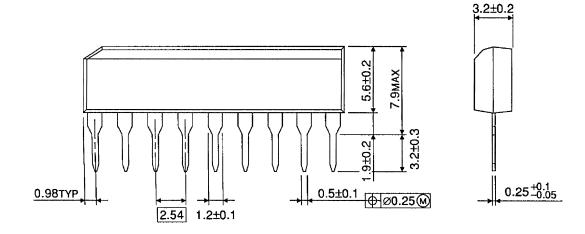
Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

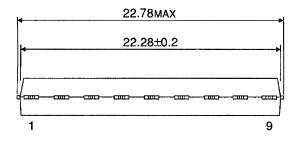
Utmost care is necessary in the design of the output line, VCC and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

# **PACKAGE DIMENSIONS**

SIP9-P-300-2.54A

Unit: mm





Weight: 0.92 g (Typ.)

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About solderability, following conditions were confirmed

- Solderability
  - (1) Use of Sn-63Pb solder Bath
    - · solder bath temperature = 230°C
    - · dipping time = 5 seconds
    - · the number of times = once
    - · use of R-type flux
  - (2) Use of Sn-3.0Ag-0.5Cu solder Bath
    - · solder bath temperature = 245°C
    - · dipping time = 5 seconds
    - · the number of times = once
    - · use of R-type flux

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030619EBA

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